



Material Content Data Sheet



Sales Product Name		SPD02N60C3		Issued		20. July 2018		
MA#		MA001364022						
Package		PG-TO252-3-341		Weight*		381.07 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.473	0.39	0.39	3865	3865
leadframe	non noble metal	iron	7439-89-6	0.248	0.07		652	
	inorganic material	phosphorus	7723-14-0	0.075	0.02		196	
	non noble metal	copper	7440-50-8	248.124	65.09	65.18	651117	651965
wire	non noble metal	aluminium	7429-90-5	0.409	0.11	0.11	1074	1074
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.745	0.46		4580	
	plastics	brominated resin	-	1.870	0.49		4907	
	organic material	carbon black	1333-86-4	1.995	0.52		5234	
	plastics	epoxy resin	-	16.830	4.42		44164	
	inorganic material	silicondioxide	60676-86-0	102.226	26.83	32.72	268258	327143
leadfinish	non noble metal	tin	7440-31-5	3.787	0.99	0.99	9937	9937
plating	non noble metal	nickel	7440-02-0	0.515	0.14	0.14	1352	1352
solder	noble metal	silver	7440-22-4	0.044	0.01		117	
	non noble metal	tin	7440-31-5	0.036	0.01		93	
	non noble metal	lead	7439-92-1	1.697	0.45	0.47	4454	4664
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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